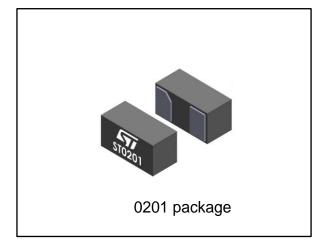


ESDZL5-1F4

Low clamping, low capacitance unidirectional single line ESD protection

Datasheet - production data



Features

- Low clamping voltage
- Unidirectional device
- Low leakage current
- 0201 package
- Ultra-low PCB area: 0.18 mm²
- ECOPACK[®]2 compliant component
- Exceeds the following standard:
 - IEC 61000-4-2 level 4 = ±30 kV (air discharge) and ±15 kV (contact discharge)

Applications

Where transient overvoltage protection in ESD sensitive equipment is required, such as:

- Smartphones, mobile phones and accessories
- Tablets and notebooks
- Portable multimedia devices and accessories
- Wearable, home automation, healthcare
- Highly integrated systems

August 2017

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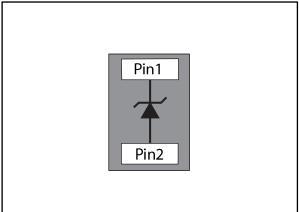
This is information on a product in full production.

Description

The ESDZL5-1F4 is a unidirectional single line TVS diode designed to protect data lines or other I/O ports against ESD transients.

The device is ideal for applications where both reduced line capacitance and board space saving are required.

Figure 1: Functional diagram



1 Characteristics

Table 1: Absolute ratings (T_{amb} = 25 °C)

Symbol	Para	Value	Unit	
V _{PP}	Peak pulse voltage	Contact discharge Air discharge	15 30	kV
P _{PP}	Peak pulse power dissipation (8	60	W	
I _{PP}	Peak pulse current (8/20 µs)	7	А	
Tj	Operating junction temperature	-55 to +150	°C	
T _{stg}	Storage temperature range	-65 to +150	°C	
TL	Maximum lead temperature for	260	°C	

Figure 2: Electrical characteristics (definitions)

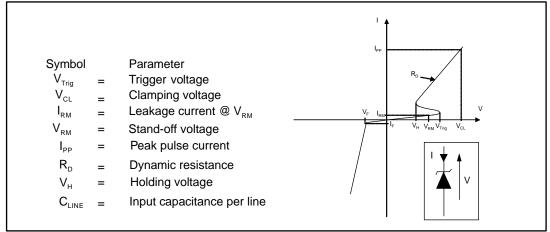


Table 2: Electrical characteristics (T_{amb} = 25 °C)

Symbol	Test condition		Тур.	Max.	Unit
VF	I _F = 10 mA	0.7		0.9	V
V _{Trig}	Higher voltage than V_{Trig} guarantees the protection turn-on	5.8		10	V
Vн	Lower voltage than V_H guarantees the protection turn-off $^{(1)}$	4.0	4.6		V
V _{RM}				5.5	V
I _{RM}	V _{RM} = 5.5 V			100	nA
VcL	8 kV contact discharge after 30 ns, IEC 61000-4-2-Pin1 to Pin2		9.5		V
V _{CL}	8 kV contact discharge after 30 ns, IEC 61000-4-2-Pin2 to Pin1		3		V
V _{CL}	8/20 μs waveform, $I_{PP} = 7$ A			10	V
CLINE	$F = 1 \text{ MHz}, V_{\text{LINE}} = 0 \text{ V}, V_{\text{OSC}} = 30 \text{ mV}$		7.5	9.5	pF
RD	Pulse duration 100 ns		0.2		Ω

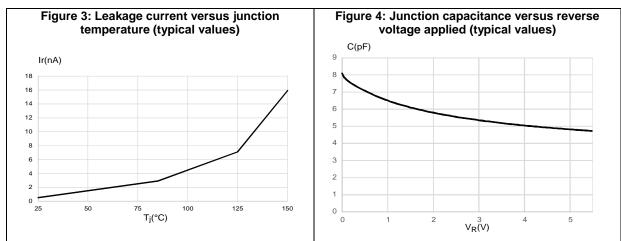
Notes:

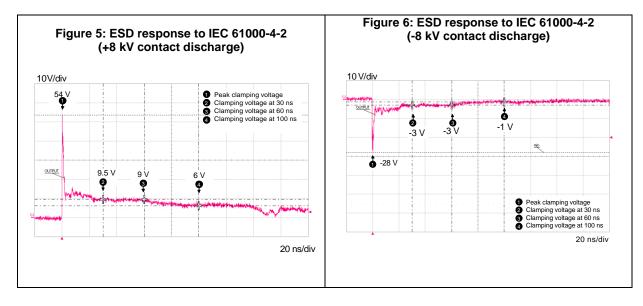
 $^{(1)}$ Application note: when used to protect a line connected to a DC source, the DC voltage must be lower than the minimum V $_{\rm H}$ to enable the diode to return to its non-conducting state after the transient.

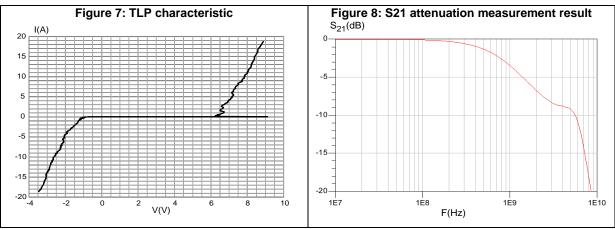


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1.1 Characteristics (curves)







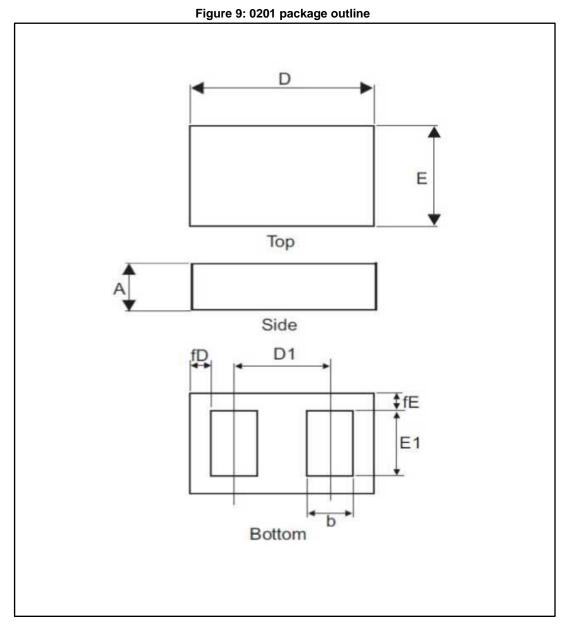
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2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK[®] is an ST trademark.

2.1 0201 package information





The marking codes can be rotated by 90 ° or 180° to differentiate assembly location.In no case should this product marking be used to orient the component for its placement on a PCB. Only pin 1 mark is to be used for this purpose.

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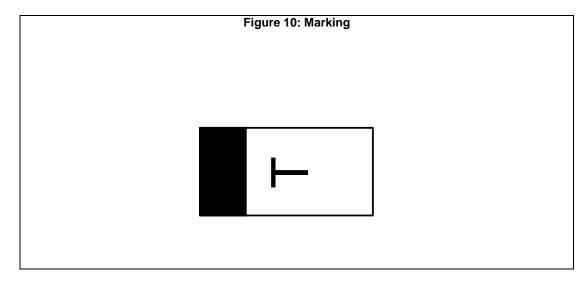


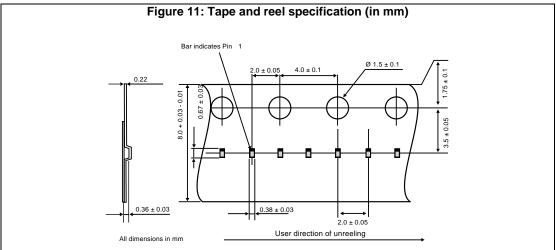
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Package information

Table 3: 0201 package mechanical data					
	Dimensions				
Ref.	Millimeters				
	Min.	Тур.	Max.		
A	0.270	0.300	0.330		
b	0.1675	0.1875	0.2075		
D	0.560	0.580	0.600		
D1		0.3375			
E	0.260	0.280	0.300		
E1	0.205	0.225	0.245		
fD	0.0175	0.0275	0.0375		
fE	0.0175	0.0275	0.0375		

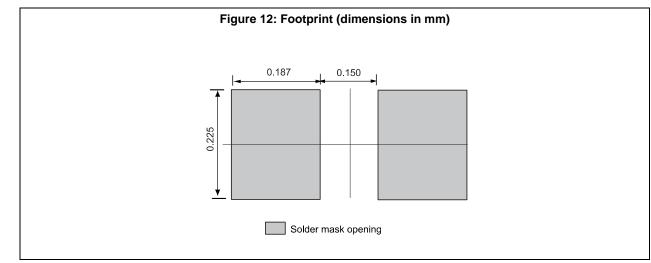




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3 Recommendation on PCB assembly

3.1 Footprint

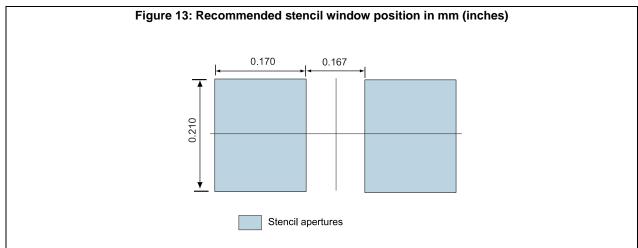


1. SMD footprint design is recommended.

3.2 Stencil opening design

Recommended design reference

 a. Stencil opening thickness: 75 μm / 3 mils



3.3 Solder paste

- 1. Halide-free flux qualification ROL0 according to ANSI/J-STD-004.
- 2. "No clean" solder paste is recommended.
- 3. Offers a high tack force to resist component movement during high speed.
- 4. Use solder paste with particle size 20-38 $\mu m.$

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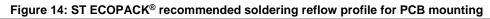
3.4 Placement

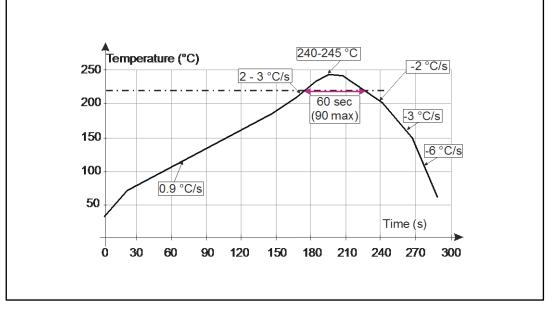
- 1. Manual positioning is not recommended.
- 2. It is recommended to use the lead recognition capabilities of the placement system, not the outline centering
- 3. Standard tolerance of ± 0.05 mm is recommended.
- 4. 1.0 N placement force is recommended. Too much placement force can lead to squeezed out solder paste and cause solder joints to short. Too low placement force can lead to insufficient contact between package and solder paste that could cause open solder joints or badly centered packages.
- 5. To improve the package placement accuracy, a bottom side optical control should be performed with a high resolution tool.
- 6. For assembly, a perfect supporting of the PCB (all the more on flexible PCB) is recommended during solder paste printing, pick and place and reflow soldering by using optimized tools.

3.5 PCB design preference

- 1. To control the solder paste amount, the closed via is recommended instead of open vias.
- 2. The position of tracks and open vias in the solder area should be well balanced. A symmetrical layout is recommended, to avoid any tilt phenomena caused by asymmetrical solder paste due to solder flow away.

3.6 Reflow profile







Minimize air convection currents in the reflow oven to avoid component movement.



4 Ordering information

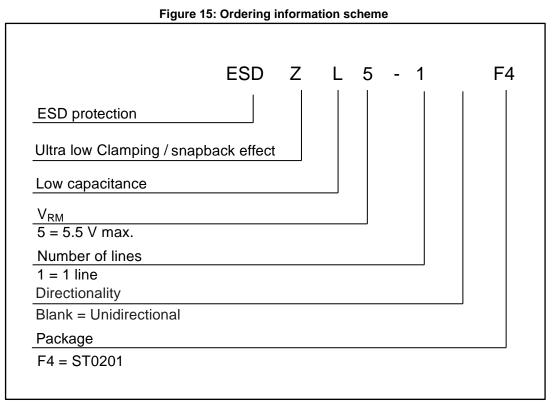


Table 4: Ordering information

Order code	Marking ⁽¹⁾	ing ⁽¹⁾ Package Weight		Base qty.	Delivery mode	
ESDZL5-1F4	Т	0201	0.116 mg	15000	Tape and reel	

Notes:

 $^{(1)}\mbox{The}$ marking can be rotated by multiples of 90° to differentiate assembly location

5 Revision history

Table 5: Document revision history

Date	Revision	Changes
01-Jun-2017	1	First issue.
28-Jul-2017	2	Updated footprint title.
17-Aug-2017 3		Updated Figure 6: "ESD response to IEC 61000-4-2 (-8 kV contact discharge)". Minor text corrections in the Features and Description.



ESDZL5-1F4

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